



Leibniz Institute  
for high  
performance  
microelectronics

# Open PDK with Open EDA Tools - Challenges and Future needs

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# IHP at a Glance



## Positioning

- ❑ IHP is the **European research and innovation centre** for **silicon-based systems**, ultrahigh-frequency circuits and technologies
- ❑ The research focuses on **socially relevant topics** such as communication, mobility, health & environment, industry & agriculture, sustainability and security.
- ❑ **Unique selling point** of a **200mm pilot line** for state-of-the-art BiCMOS technologies, operated under **industry-like conditions, 24/7**, for the provision of prototypes and low-volume production runs.
- ❑ **Qualified technological platform** with direct access for science and industry



## Vision

*"We create foundations and prototype applications based on future silicon-based technologies and systems for a digitalised and networked world as well as for the sustainable preservation of our natural living conditions."*

# 130nm SiGe BiCMOS Technologies for RF Applications



	SG13S	SG13G2	SG13G3Cu
<b>SiGe-HBT</b> $f_t/f_{max}$	250 / 340 GHz	350 / 450 GHz	<b>470 / 650 GHz</b>
$W_{Emitter}$	170 nm	130 nm	110 nm
HBT $BV_{CEO}$	1.7 V	1.6 V	1.5 V
<b>CMOS</b> node	<b>130 nm</b>		
Active devices	Schottky diodes, Antenna diodes, PN diodes, ESD		
Varactors	NMOS Varactor		
Resistors	Poly-Si, Thin Film		Poly-Si
MIM Caps	1.5 fF / $\mu\text{m}^2$ (Al) 2.1 fF / $\mu\text{m}^2$ (Cu)	1.5 fF / $\mu\text{m}^2$ (Al) 2.1 fF / $\mu\text{m}^2$ (Cu)	2.1 fF / $\mu\text{m}^2$
Metallization	7 Layers AL incl. 2 & 3 $\mu\text{m}$ layers or *Cu: 4 + 2 (3 $\mu\text{m}$ ) Al: 2 (3 $\mu\text{m}$ )	7 Layers AL incl. 2 & 3 $\mu\text{m}$ layers or *Cu: 4 + 2 (3 $\mu\text{m}$ ) Al: 2 (3 $\mu\text{m}$ )	*Cu: 4 + 2 (3 $\mu\text{m}$ ) Al: 2 (3 $\mu\text{m}$ )

\*Cu BEOL from X FAB

- Target are **high end developments** for RF & Terahertz frequencies, cryo and space applications
- SG13S & SG13G2 are qualified and ready for **Low Volume of high end products** **SG13G2** technology was selected for the development of an **open PDK**
- SG13G3Cu is early access - qualification scheduled 2025

# Motivation for IHP's open Process Design Kit (PDK) initiative

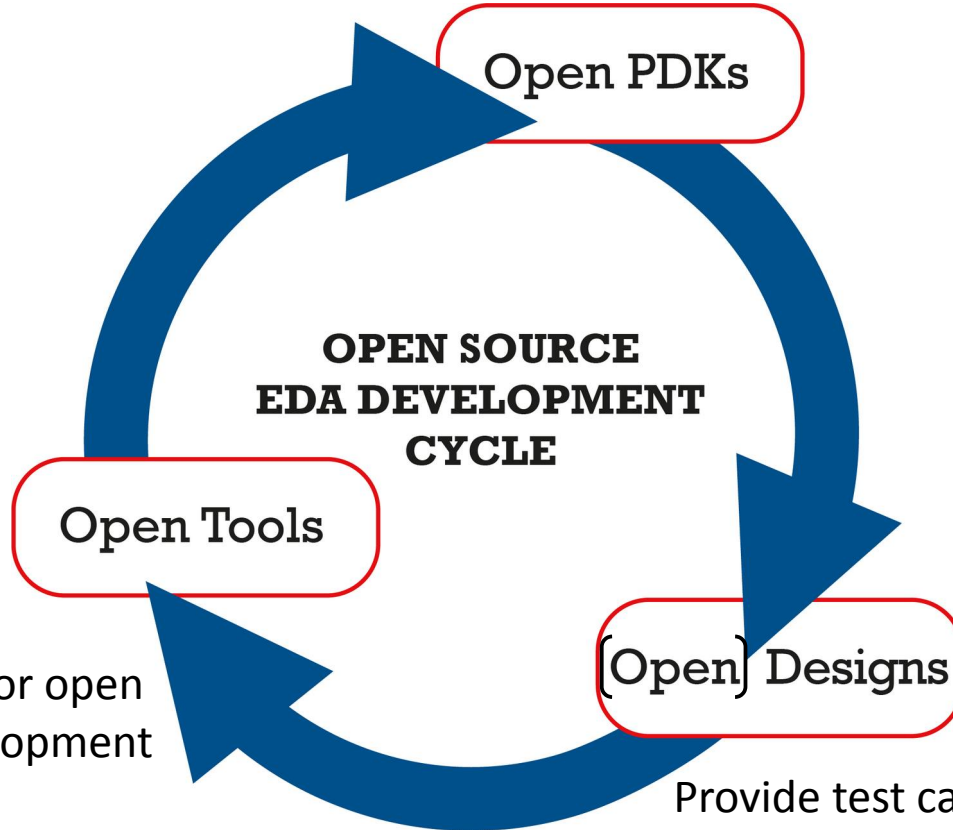


- **Simplify access to education** materials for chip designers and to attract young people to get into chip design process
- Provide **low threshold (cost/technological) access to technology & PDK** for chip designer, academic projects
- **Be a pioneer** in demonstrating the possibilities of open source EDA software
- To **convince commercial fabs** to support the open source approach
- Support chip design possibilities for **advance IC design projects** by **StartUp, SMEs and commercial companies**

# Open EDA cycle to push open hardware development



Enable open and worldwide collaboration on development of the PDK, co-development of tools and PDK features

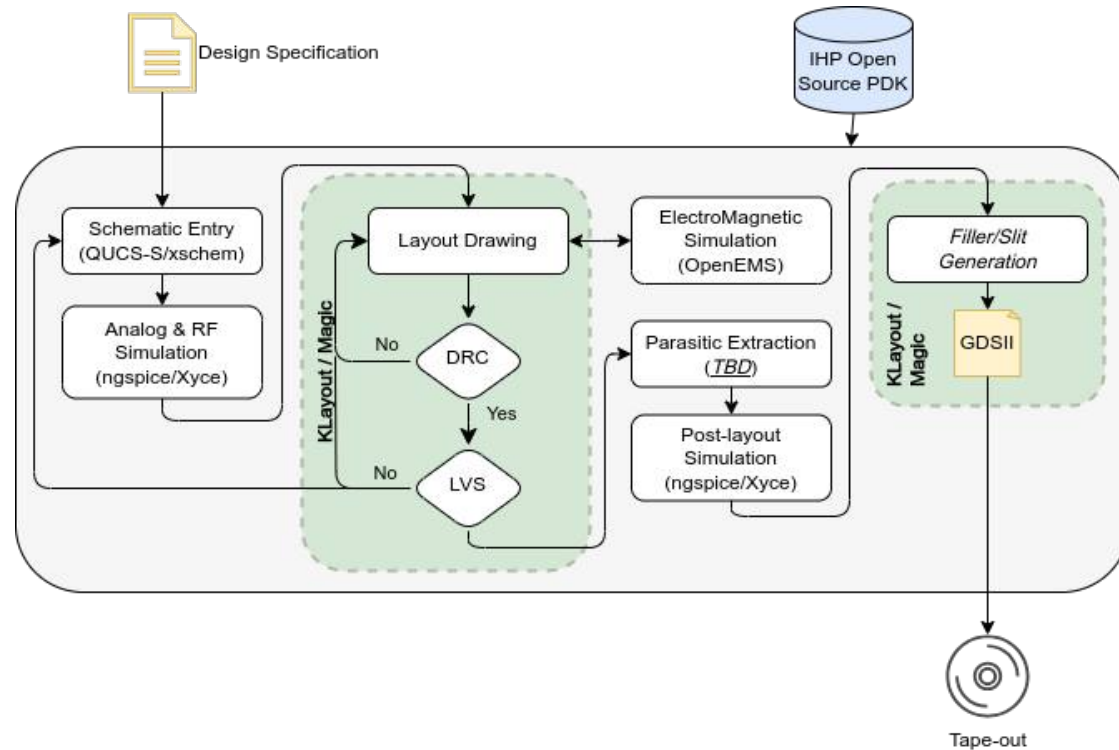


Open EDA Tools for more than 20 years  
**but**  
Open PDK was the missing piece to get  
the cycle going

Provides platform for open EDA software development and possibility for collaborative design projects

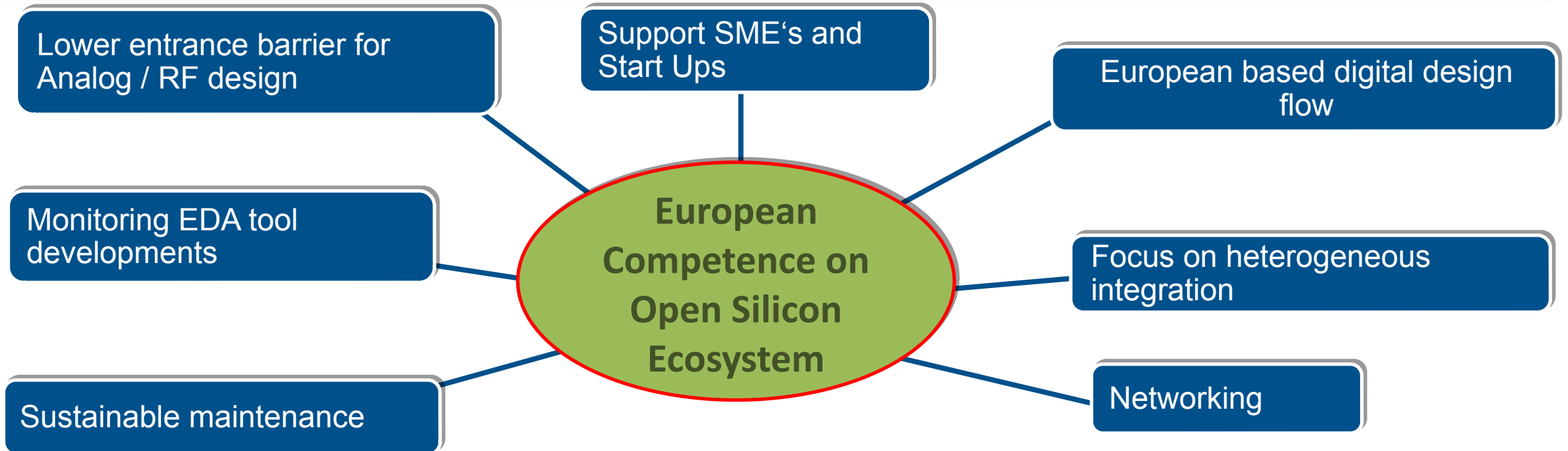
Provide test cases, regression tests, benchmarks, use cases, user stories, feedback & error reports

# Analog/RF Open Source Design Flow / Challenges



- Open EDA Tools often handled by individual enthusiasts or small groups
- Lack of a complete open source analog design flow
- Open IC designs needed to improve Open EDA tools and foster its developments
- Open Process Design Kits are not available in EU
- No European concept for sustainable maintenance of the Open PDKs and Open EDA tools

# Future Needs



➡ We need a European Open Source Silicon Ecosystem

- Is a **European Open Silicon Hub** possible?
- Will there be projects targeting open source to **get initial funding**?
- Can a **European Foundation** or associated fund support this?

# Acknowledgment



- Thanks to open source community SemiMod, ETH Zurich, Uni Linz, ChipFlow, Staf Verhaegen (PDKMaster), M. Koefflerlein (klayout), D. Warning, H. Vogt (ngspice), M. Brinson (Qucs-S), and many more ...
- Thanks to different public founded German projects:
  - VE-HEP (16KIS1339K)  
<https://elektronikforschung.de/projekte/ve-hep-1>
  - IHP Open130-G2 (16ME0852)  
<https://www.elektronikforschung.de/projekte/ihp-open130-g2>
  - FMD-QNC (16ME0831)  
<https://www.elektronikforschung.de/projekte/fmd-qnc>
  - Design tools for sovereign chip development with open source (DE:Sign) – starting now May 2024

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